

# Pre-prototype GEM panel for LP1

Japanese TPC group  
Akira Sugiyama  
Saga Univ.

What is Large Prototype

Why we need pre-prototype test

What we are going to make

GEM panel  
100um GEM

Schedule

# Large prototype TPC in LC TPC collab.

Mom. resolution

dead space

Large area MPGD

calibration

reconstruction efficiency

under non-uniform field

low material TPC

could be studied in LargePrototype in LC-TPC

## Conceptual Design at moment

Endplate

+

small/medium size panel

1 MPGD/panel ??

Gas seal by endplate

stand for pressure

Size of panel ??

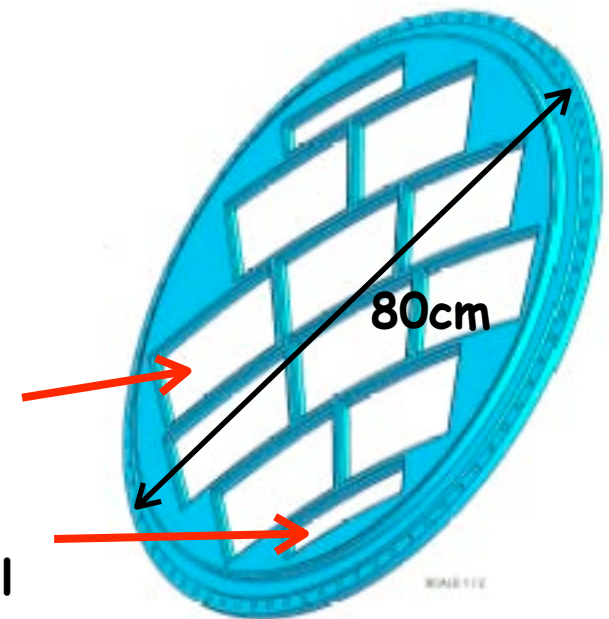
Readout electronics

—>std. RO @LP1

GEM/MM panel

for Pixel

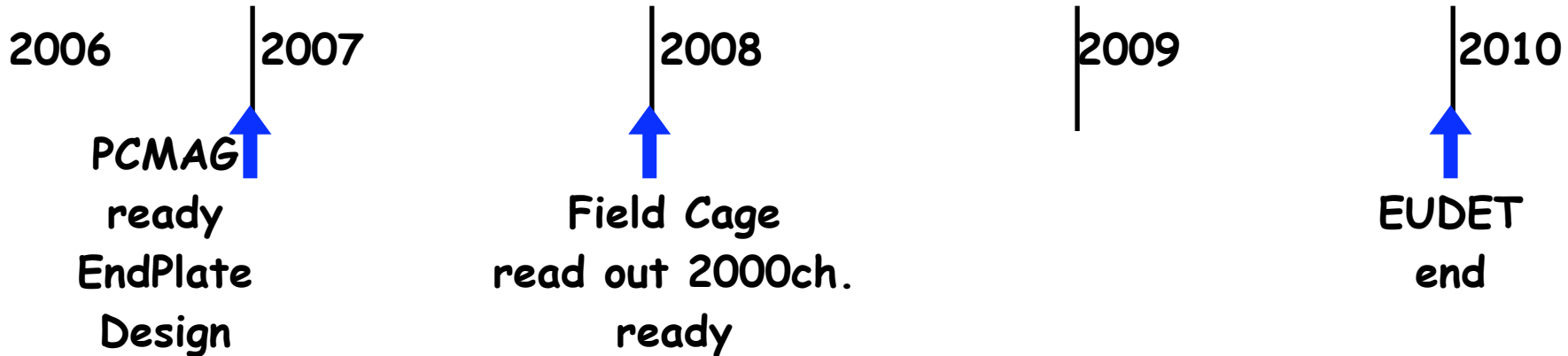
LP Endplate



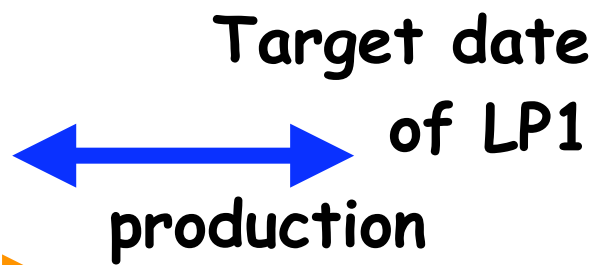
Alignment using tracks  
Efficiency at boundary

# LC-TPC prototype study schedule

EUDET



realistic electronics  
realistic config.



**"Pre-PROTO"**

though many issues are not fixed yet

# What we want to do at Pre-PROTO

## Production of GEM panel

minimize dead area due to GEM support frame

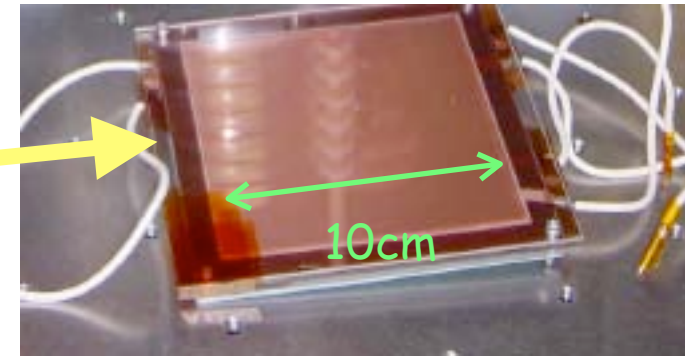
specially in radial direction

we hope to remove radial frame

to avoid loss of series of hit info.

can we mount GEM properly?

how do we stretch GEM?



## Pad plane

Proper Pad size

Analytic formula teach us max. pad width  
in order to avoid hod-scope effect  
diffusion in GEMs must be larger than  
~0.3 of pad pitch

~300um w/ 5mm thick

for the most of gas

1mm pitch of pad width

length angular dep. of

$\sigma_0 \sim 30\mu\text{m}$  @6mm for 50GeV track

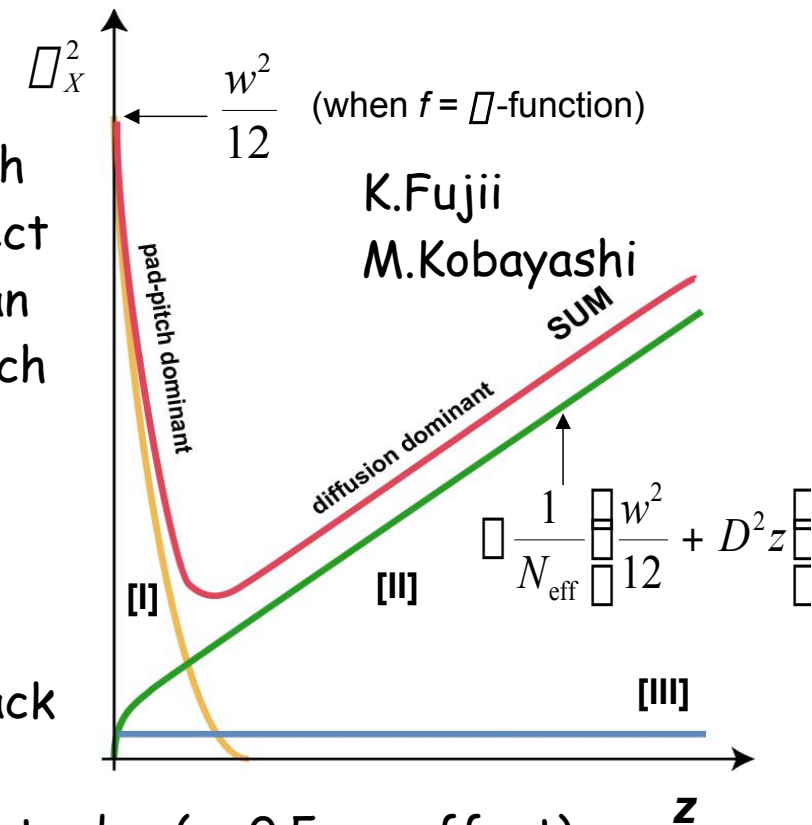
staggered pad layer by layer

forget about loss of a half pad at edge ( ~0.5mm effect)

SIZE of panel under discussion

We choose Dan's early design

( Final panel size will be decided soon )



# GEM structure

narrow frame (mount mechanism)

double GEM(100um thick) : high gain

simple structure

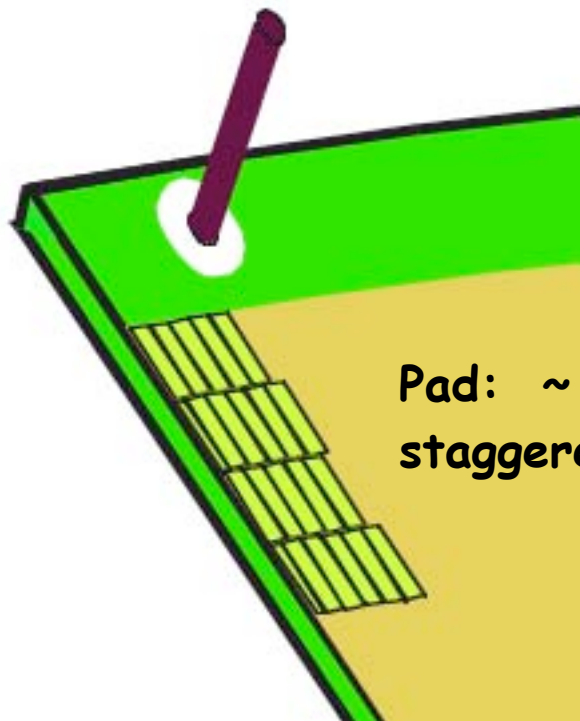
how to provide HV

low capacitance ( 100um + division )

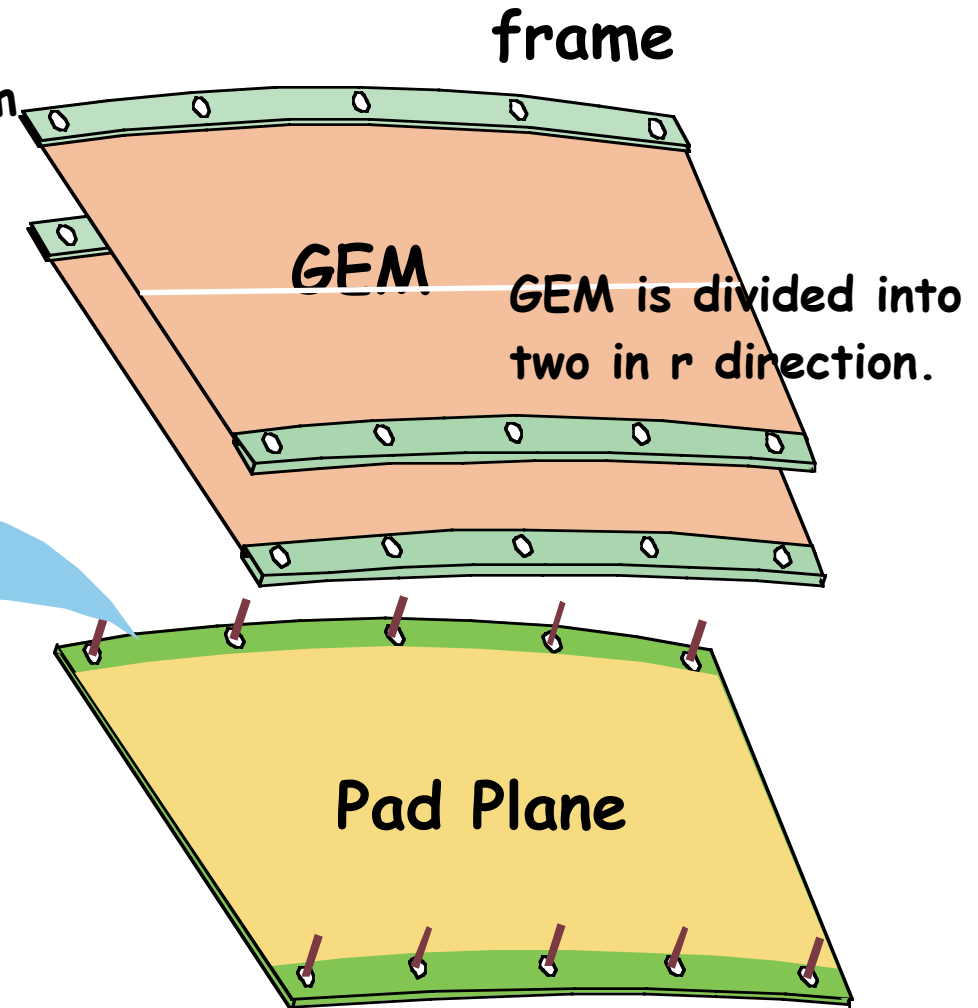
F.Sauli suggested  $< 70\text{cm}^2$  @50um

field shaping at frame

GEM is stretched by the post



Pad:  $\sim 1 \times 5.5 \text{ mm}^2$   
staggered a half pitch

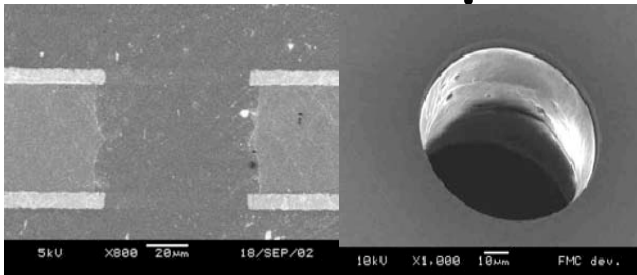


# GEM

We are considering to use 100um GEM  
in order to simplify the structure on the panel

Double GEM is simpler than triple  
100um GEM provides good enough gain

Scienergy CO.(Japanese GEM company)  
produce 100um thick GEM



Laser etching

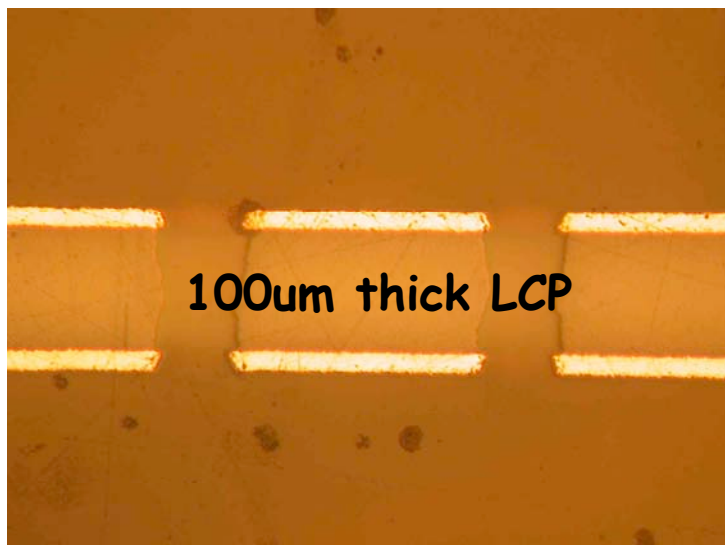
straight hall

instead of bi-conical in wet

material choice

LCP(liquid Crystal Polymer)

easier to be processed than PI



100um thick LCP

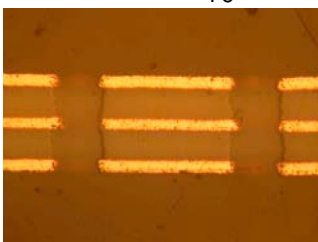
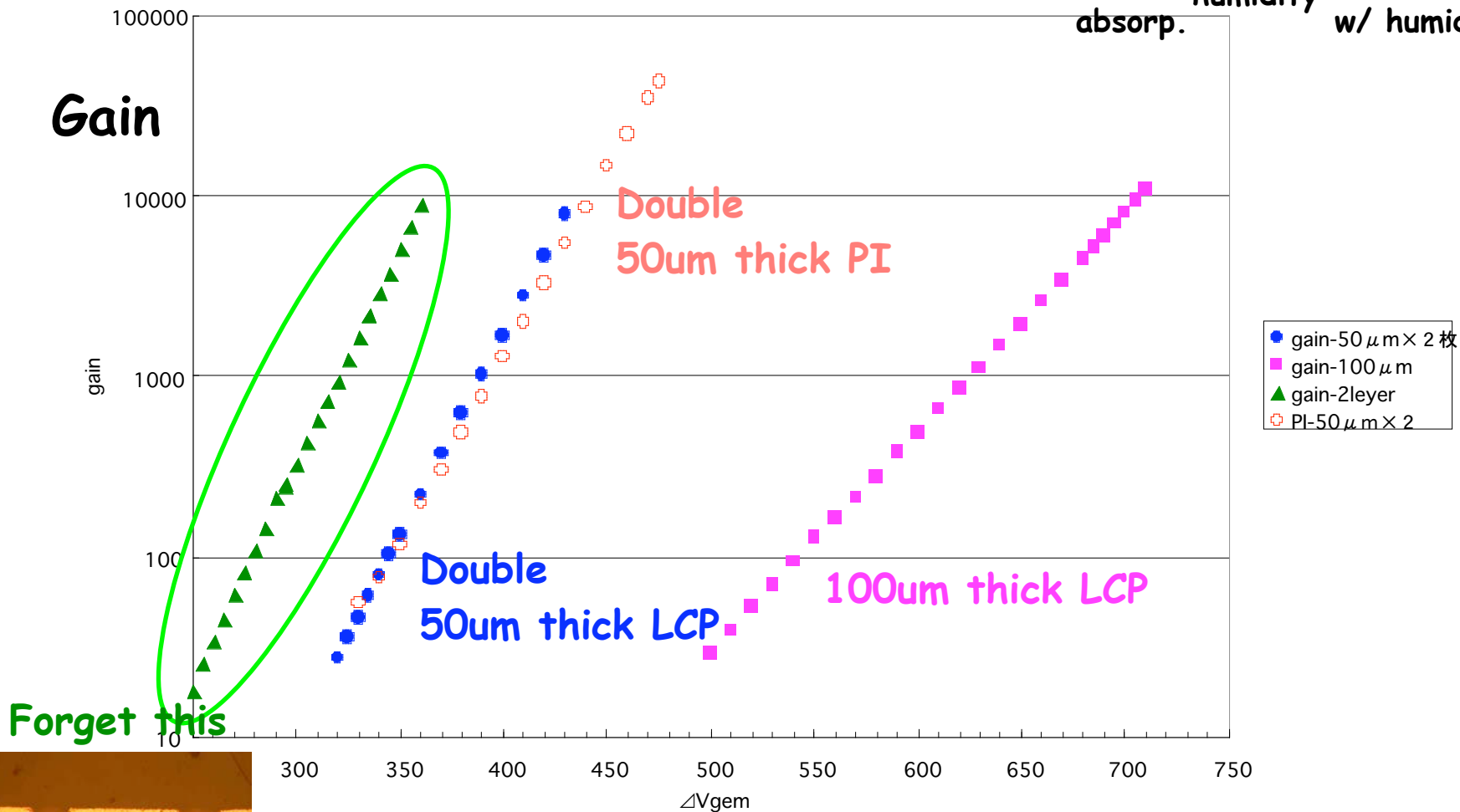
# Property of 100um thick GEM

表1 ポリイミドと LPC の特性比較

特性	吸水率	吸湿率	湿度膨張係数	比誘電率 $\epsilon_r$	誘電正接 $\tan \delta$
単位	%	%	ppm/%RH	(at 1GHz)	(at 1GHz)
PI	3.1	1.6	30	3.51	0.0113
LPC	0.04	<0.04	1	3.20	0.0024

PolyImide  
LCP  
 $\Delta V_{gem}$  vs gain

water humidity exp.rate  
absorp. w/ humidity



$\Delta V_{GEM}$

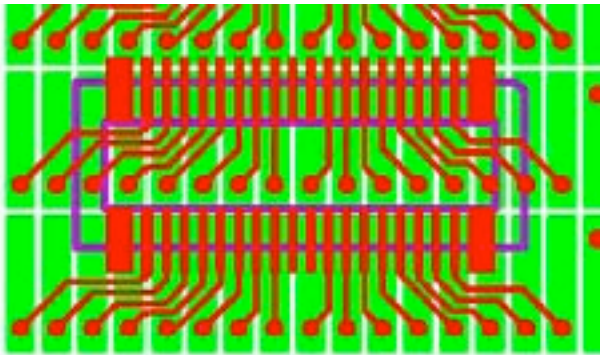




# Pad size

Actual Pad size is limited by arrangement of connectors  
conn. size is 5mm x 11.5 mm  
but soldering / line design need more space ~ 8.5mm x 15mm

Leif's drawing



20 layers

192 pads /layer

Length of pad pitch 5.55 mm

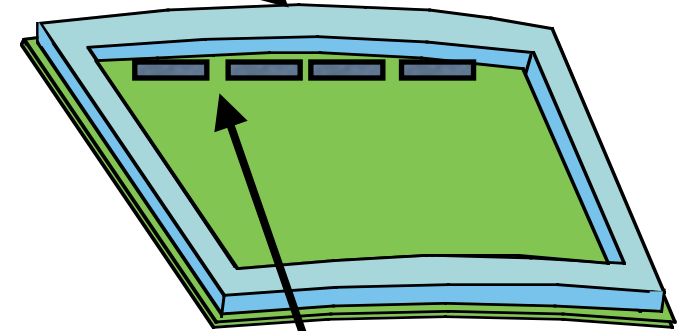
Width of pad pitch 1.08 mm @innermost

1.18 mm @outermost

# of connectors

10 lyr x 12 con./lyr

supporting structure  
to endplate  
2cm wide



connectors

# Schedule

Nov.

Dec.

Jan.

Feb.

Mar.

test of Mount mechanism



now: We are facing to ...



GEM production

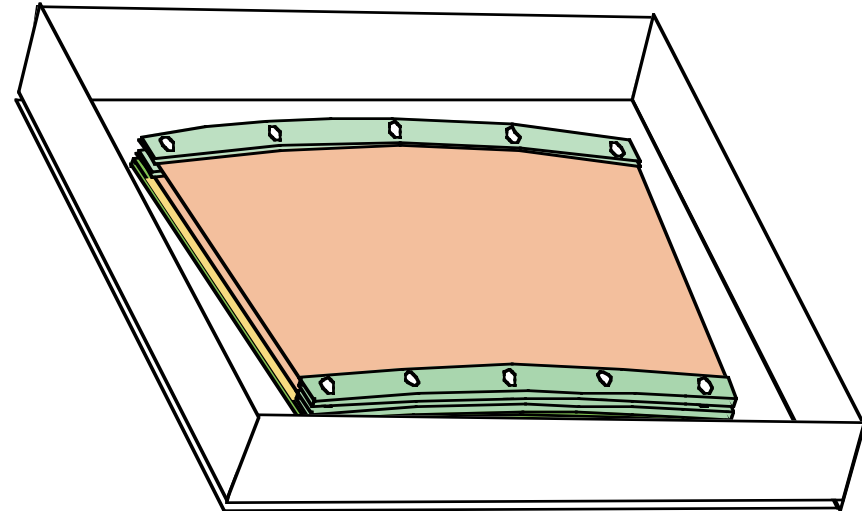


Pad Plane production

Assembly

TEST

Gain check  
over the panel



# Summary

We started to make pre-prototype  
as R&D for LP1

how to minimize dead region due to GEM support

We will try to release every information about this study

please give us any suggestions/idea for pre-prototype study  
AND be a collaborator

we want to work together !